REPLACEMENT SHEET

APPLN. FILING DATE: OCTOBER 13, 2000
TITLE: METHOD FOR MANUFACTURING ELECTRONIC PARTS
INVENTOR(S): AKIO KATSUBE ET AL.
APPLN. NO.: 09/689,774

SHEET 1 OF 6

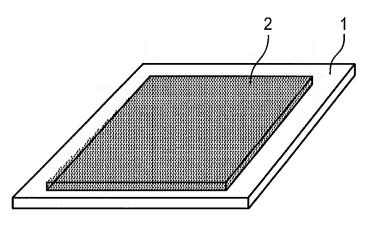


FIG. 1A

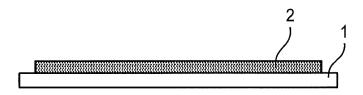
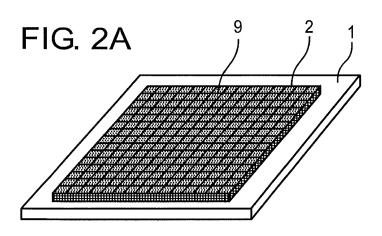
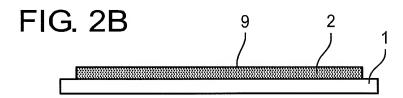
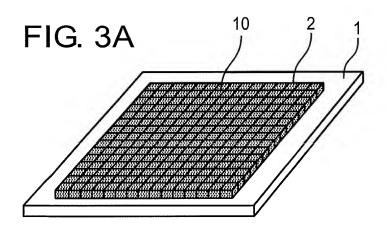


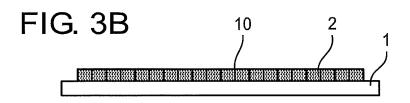
FIG. 1B

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TITLE: METHOD FOR MANUFACTURING ELECTRONIC PARTS
INVENTOR(S): AKIO KATSUBE ET AL.
APPLN. NO.: 09/689,774
SHEET 2 OF 6









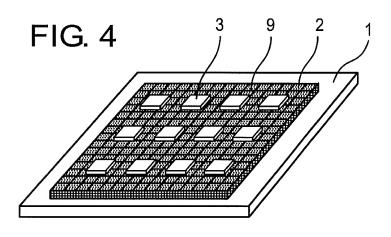
REPLACEMENT SHEET

APPLN. FILING DATE: OCTOBER 13, 2000

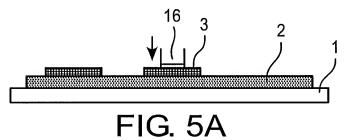
TITLE: METHOD FOR MANUFACTURING ELECTRONIC PARTS

INVENTOR(S): AKIO KATSUBE ET AL. APPLN. NO.: 09/689,774

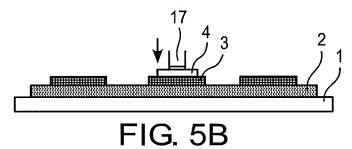
SHEET 3 OF 6



# SUBSTRATE MOUNTING PROCESS



# **DIE BONDING PROCESS**



WIRE BONDING PROCESS

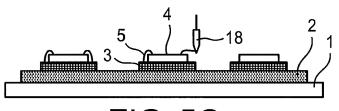


FIG. 5C

REPLACEMENT SHEET

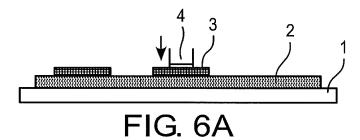
APPLN. FILING DATE: OCTOBER 13, 2000

TILE: METHOD FOR MANUFACTURING ELECTRONIC

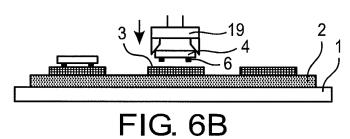
PARTS
INVENTOR(S): AKIO KATSUBE ET AL.
APPLN. NO.: 09/689,774

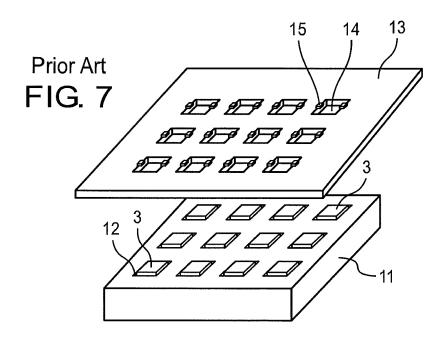
SHEET 4 OF 6

## SUBSTRATE MOUNTING PROCESS



## **BUMP BONDING PROCESS**

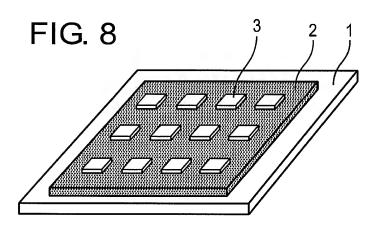




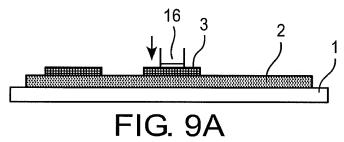
REPLACEMENT SHEET
APPLN. FILING DATE: OCTOBER 13, 2000
TITLE: METHOD FOR MANUFACTURING ELECTRONIC

PARTS
INVENTOR(S): AKIO KATSUBE ET AL.
APPLN. NO.: 09/689,774

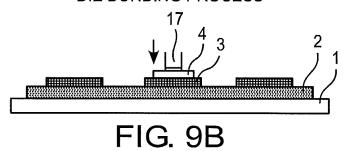
SHEET 5 OF 6



# SUBSTRATE MOUNTING PROCESS



# **DIE BONDING PROCESS**



### WIRE BONDING PROCESS

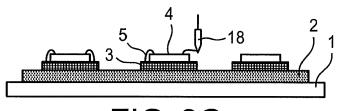


FIG. 9C

### REPLACEMENT SHEET

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INVENTOR(s): AKIO KATSUBE ET AL.
APPLN. No.: 09/689,774
SHEET 6 OF 6

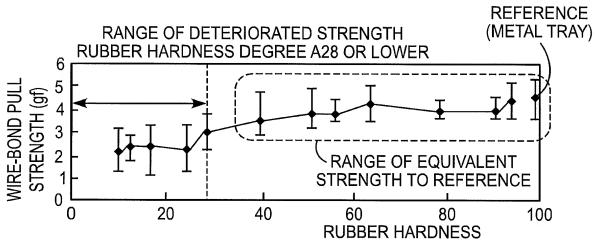
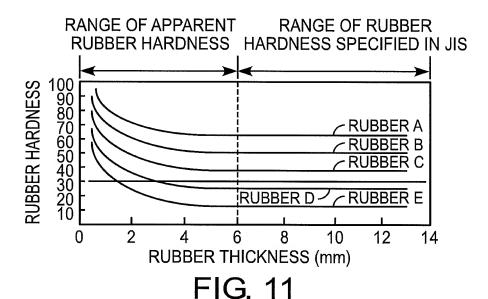
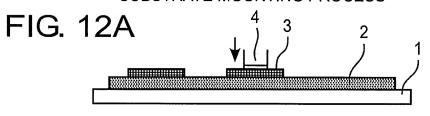


FIG. 10



SUBSTRATE MOUNTING PROCESS



### **BUMP BONDING PROCESS**

